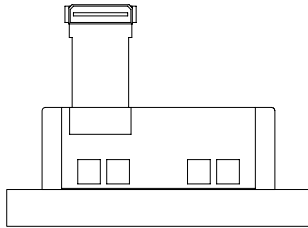


WIREBONDING CHECKLIST FOR CMS TOB HYBRIDS
FOR 8060 WIREBONDER

Program: TOB4CHP or TOB6CHP

Part Orientation:



1. Pitch Adapter to Chip Bonds

Lead Reference System (L): Pitch Adapter

Die Reference System (U): Chip

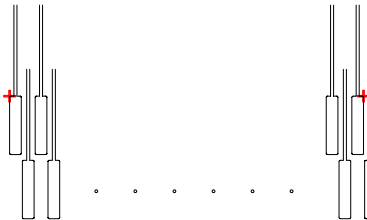
operator point 1:
1. pad, bottom left corner

operator point 2:
63. pad, bottom right corner



operator point 1:
1. pad, top left corner

operator point 2:
63. pad, top right corner



First Bond: Pitch Adapter

Second Bond: Chip

Bond time: 20 ms

Bond time: 25 ms

USG Current: 60 mA

USG Current: 50 mA

Force: 28

Force: 35

Tip: 20 mils

Tip: 20 mils

Loop Parameters:

Tail Parameters:

Shape: square

Feed: 75

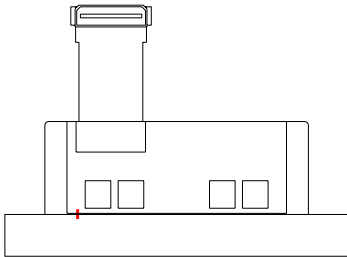
Loop height: short bonds 33 mils, long bonds 48 mils

Clear height: short bonds 100 mils, long bonds 100 mils

clamp close at loop

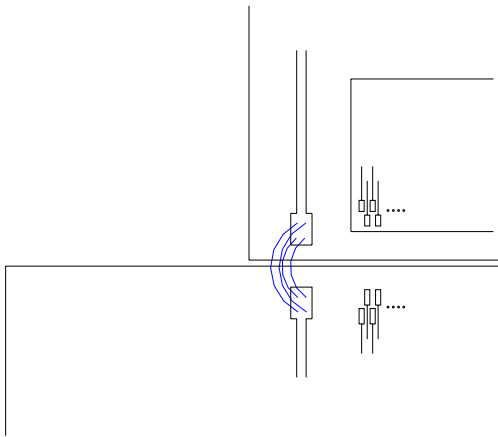
2. Hybrid Bias Bonds

Bias Bonds Location:



Pitch Adapter to Gold Pad on Hybrid:

Place 4 bonds, 2 short, 2 long



First Bond: Pitch Adapter

Bond time: 20ms

USG Current: 60 mA

Force: 28

Tip: 20 mils

Loop Parameters:

Shape: square

Loop height: short bonds 60 mils, long bonds 70 mils

Clamp close at loop

Second Bond: Gold

Bond time: 35 ms

USG Current: 65 mA

Force: 25

Tip: 20 mils

Tail Parameters:

Feed: 75